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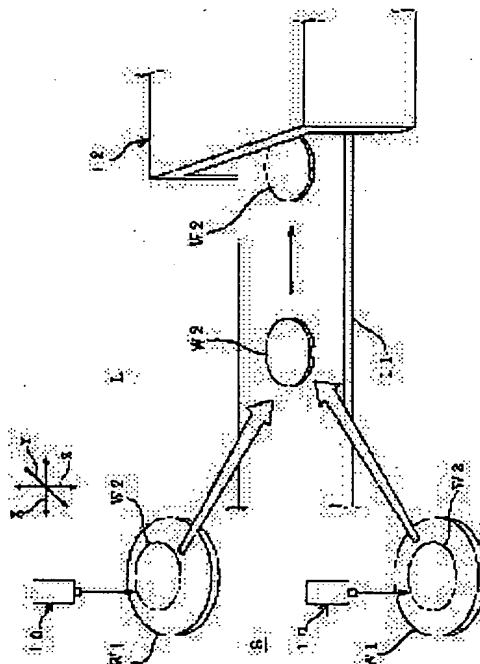
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(54) LARGE-DIAMETER WAFER ESTIMATING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To utilize a small-diameter wafer estimating line for estimating a large-diameter wafer.

SOLUTION: By cutting a large-diameter wafer W1 of 300 mm diameter, a small-diameter wafer W2 of 200 mm diameter is created. Thereafter, by transferring the obtained small-diameter wafer W2 onto a line conveyor 11 of an evaluating line L for the wafers of 200 mm, its necessary evaluating tests are performed in various wafer evaluation apparatuses 12 provided successively on this line L. In this way, the evaluation of the large-diameter wafer W1 can be performed by the existent evaluating line L for the wafers of 200 mm which is provided in factory, etc. Additionally at cutting, the large-diameter wafer W2 is cut with a laser beam to make its cutting workability improvable.



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